19-3861; Rev 1; 12/07

power-down mode.

+3.465V output high levels.

an exposed paddle.

LCDs

Cell Phones

Digital Cameras

EVALUATION KIT

AVAILABLE

22-Bit, Low-Power, 5MHz to 10MHz **Serializer and Deserializer Chipsets**

General Description

The MAX9223/MAX9224 serializer/deserializer chipsets

reduce wiring by serializing 22 bits onto a single differen-

tial pair. 22 bits are serialized in each cycle of the paral-

lel input clock resulting in a 110Mbps to 220Mbps net

serial-data rate ideal for cell phone QVGA and QCIF dis-

plays. The MAX9223 serializes the 18-bit RGB, VSYNC, HSYNC, and two control signals from the baseband

processor to reduce wiring through the hinge to the LCD

controller. The 2-wire serial interface uses low-current dif-

ferential signaling (LCDS) for low EMI, high commonmode noise immunity, and ground-shift tolerance. The

MAX9223/MAX9224 automatically identify the word

boundary in serial data in case of signal interruption. The

MAX9224 power-down is controlled by the MAX9223.

The MAX9223 and MAX9224 consume 3.5µA or less in

The MAX9223 serializer operates from a single +2.375V

to +3.465V supply and accepts +1.71V to +3.465V

inputs. The MAX9224 deserializer operates from a +2.375V to +3.465V core supply and has a separate output buffer supply (VDDO), allowing +1.71V to

The MAX9223/MAX9224 are specified over the -40°C to +85°C extended temperature range and are available in 28-pin TQFN (4mm x 4mm x 0.8mm) packages with

Features

- Ideal for Serializing Cell Phone LCD or Imager **Parallel Interface**
- MAX9223 Serializes 18-Bit RGB, VSYNC, HSYNC, and Two Control Signals
- LCDS Rejects Common-Mode Noise
- Automatic Location of Word Boundary After Signal Interruption
- Power-Down Control Through the Serial Link
- Power-Down Supply Current 0.5µA (max)-MAX9223 3.0µA (max)-MAX9224
- +2.375V to +3.465V Core Supply Voltage
- Parallel I/O Interfaces Directly to 1.8V to 3.3V Logic
- ±15kV Human Body Model ESD Protection
- ♦ -40°C to +85°C Operating Temperature Range

Ordering Information

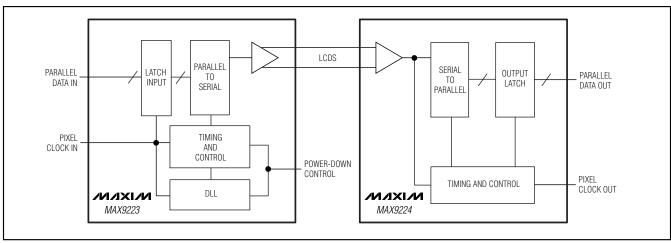
PART	TEMP RANGE	PIN- PACKAGE	PKG CODE
MAX9223ETI	-40°C to +85°C	28 TQFN-EP*	T2844-1
MAX9223ETI+	-40°C to +85°C	28 TQFN-EP*	T2844-1
MAX9224ETI	-40°C to +85°C	28 TQFN-EP*	T2844-1
MAX9224ETI+	-40°C to +85°C	28 TQFN-EP*	T2844-1

+Denotes lead-free package.

*EP = Exposed paddle.

Pin Configurations appear at end of data sheet.

Typical Application Circuit



Applications

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND V _{DDO} to GND	
Serial Interface (SDO+, SDO-, SDI+, SDI-) to GND	0.5 // to $+ 4.0$ //
Single-Ended Inputs (DIN_, PCLKIN,	
PWRDN) to GND Single-Ended Outputs (DOUT,	-0.5V to (V _{DD} + 0.5V)
PCLKOUT) to GNDC	
Continuous Power Dissipation (T _A = +70°C 28-Pin TQFN (4mm x 4mm x 0.8mm)	2)
Multilayer PCB (derate 28.6mW/°C	
above +70°C)	2286mW

Single-Layer PCB (derate 20.8mW/°C	
above +70°C)	1667mW
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
ESD Protection (Human Body Model)	
SDO+, SDO-, SDI+, SDI- to GND	> ±15kV
All Other Pins	> ±2kV

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS—MAX9223

 $(V_{DD} = +2.375V \text{ to } +3.465V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{DD} = +2.5V, T_A = +25^{\circ}C.)$ (Notes 1, 2)

PARAMETER	SYMBOL	CON	DITIONS	MIN	ТҮР	MAX	UNITS
SINGLE-ENDED INPUTS (PCLKIN,	DIN_, PWR	DN)					
High-Level Input Voltage	VIH			1.19		V _{DD} + 0.3	V
Low-Level Input Voltage	VIL			-0.3		+0.3	V
		$V_{IN} = 0V$ to V_{DD}		-20		+20	
Input Current	lin	$-0.3V \le V_{IN} < 0V$		-100		+100	μA
		$V_{DD} < V_{IN} \leq (V_{DD} +$	0.3V)	-100		+100	
LCDS OUTPUT (SDO+, SDO-)							
Differential Output Current (Note 3)	IODH	High level		600	643	880	
Diferential Output Current (Note 3)	IODL	Low level		200	229	300	μA
Output Short-Circuit Current	los	Shorted to 0V or VD	D			880	μA
POWER SUPPLY							
		$V_{DD} = 2.5V,$	PCLKIN = 5MHz (110Mbps)		4.4	8.2	
Supply Current	IDD	DIN_ = all low or all high	PCLKIN = 10MHz (220Mbps)		5.6	8.2	mA
Ward Oass Dathar Oversty Overst		V _{DD} = 2.5V,	PCLKIN = 5MHz (110Mbps)		4.1	10.6	
Worst-Case Pattern Supply Current	Figure 1 PCLKIN = 10MHz (220Mbps)			5.4	10.6	mA	
Power-Down Supply Current	IDDZ	All inputs = low				0.5	μA

DC ELECTRICAL CHARACTERISTICS—MAX9224

 $(V_{DD} = +2.375V \text{ to } +3.465V, V_{DDO} = +1.71V \text{ to } +3.465V, T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DD} = +2.5V, T_A = +25^{\circ}\text{C}.) \text{ (Notes 1, 2)}$

PARAMETER	SYMBOL	COND	ITIONS	MIN	ТҮР	MAX	UNITS
SINGLE-ENDED OUTPUTS (PCLKC	UT, DOUT_	_)					•
High-Level Output Voltage	VOH	V _{DDO} = +2.375V to +	-3.465V, I _{OH} = -1mA	0.8 x V _{DI}	00		V
Low-Level Output Voltage	VOL	$V_{DDO} = +2.375V \text{ to } +$	-3.465V, I _{OL} = 1mA			0.2	V
			V _{DDO} = 2.375V	-2			
Output Short-Circuit Current	los	Output shorted to ground	$V_{DDO} = 3.135V$	-9			mA
			V _{DDO} = 3.465V	-25			
LCDS INPUT (SDI+, SDI-)							
Differential Input-Current Threshold	lid				400		μA
Common-Mode Input Current	lic			-300	±500	+300	μA
		$I_{IC} = 0\mu A$ at $V_{DD} = 3.3$	3V ±5%	69	90	109	
		$I_{IC} = 0\mu A$ at $V_{DD} = 2.5$	8V ±5%	82	108	132	
Differential Input Impedance	ZID	$I_{IC} = 0\mu A$ at $V_{DD} = 2.5$	5V ±5%	95	125	153	Ω
		$I_{IC} = \pm 300 \mu A \text{ at } V_{DD}$	= 3.3V ±5%	67	91	112	
		$I_{IC} = \pm 300 \mu A \text{ at } V_{DD}$	= 2.8V ±5%	86	108	136	
Common-Mode Input Impedance	ZIC	$I_{IC} = \pm 300 \mu A$	90	167	375	Ω	
Input Capacitance	CIN	SDI+ or SDI- to groun	nd		2		V V W V mA μA μA μA
POWER SUPPLY							
Quere la Quere et (Nata A)		$V_{DD} = V_{DDO} = 2.5V$	PCLKOUT = 5MHz (110Mbps)		9	12	
Supply Current (Note 4)	ITOT	DOUT_ = all high or all low	PCLKOUT = 10MHz (220Mbps)		9	12	V V mA μA μA
Worst-Case Pattern		$C_L = 5pF, V_{DD} =$	PCLKOUT = 5MHz (110Mbps)		10	12	
Supply Current (Note 4)	Ітотw	V _{DDO} = 2.5V, Figure 2	PCLKOUT = 10MHz (220Mbps)		10	12	mA
Power-Down Supply Current (Note 4)	ITOTZ				0.08	3	μΑ
Supply Difference	V _{SD}	MAX9223 V _{DD} to MAX	X9224 V _{DD}	-5		+5	%
GROUND POTENTIAL							
Ground Difference	VGD	MAX9223 to MAX922	4 ground difference	-0.2		+0.2	V



AC ELECTRICAL CHARACTERISTICS—MAX9223

 $(V_{DD} = +2.375V \text{ to } +3.465V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{DD} = +2.5V, T_A = +25^{\circ}C.)$ (Note 3)

					, ,	
PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
PCLKIN INPUT REQUIREMENTS (F	igure 3)					
Input Rise Time	t _R				2	ns
Input Fall Time	tF				2	ns
PCLKIN Period	tP		100		200	ns
High-Level Pulse Width	tpwh		0.3 x t _P		0.7 x t _P	ns
Low-Level Pulse Width	tpwl		0.3 x t _P		0.7 x t _P	ns
Setup Time	ts		3			ns
Hold Time	tH		1			ns

AC ELECTRICAL CHARACTERISTICS—MAX9224

 $(V_{DD} = V_{DDO} = +2.375V$ to +3.465V, $C_L = 5pF$, $T_A = -40^{\circ}C$ to +85°C, unless otherwise noted. Typical values are at $V_{DD} = V_{DDO} = +2.5V$, $T_A = +25^{\circ}C$.) (Notes 3, 5)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
PCLKOUT Period	tP	Figure 4	100		200	ns
High-Level Pulse Width	tpwh	Figure 4	0.4 x t _P		0.6 x t _P	ns
Low-Level Pulse Width	tpwl	Figure 4	0.4 x t _P		0.6 x t _P	ns
Data Valid Before PCLKOUT	tvB	Figure 4	5			ns
Data Valid After PCLKOUT	tva	Figure 4	5			ns
SERIALIZER AND DESERIALIZE	R LINK					
Dower Lip Time	tPU1	From $V_{DD} = V_{DDO} = 2.375V$ when supplies are ramping up			6144 x t _P	5
Power-Up Time	tPU2	From PWRDN low to high		4096 x t _P	ns	
Power-Down Time	t PWRDN	From PWRDN high to low		2.8	10	μs

Note 1: Current into a pin is defined as positive. Current out of a pin is defined as negative. All voltages are referenced to ground. **Note 2:** Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are production

tested at $T_A = +85^{\circ}C$.

Note 3: Parameters are guaranteed by design and characterization, and are not production tested. Limits are set at ± 6 sigma. **Note 4:** $I_{TOT} = I_{DD} + I_{DDO}$.

Note 5: C_L includes probe and test jig capacitance.

MAX9223/MAX9224

ODD DOUT_

EVEN DOUT_

PCLKOUT

Test Circuits/Timing Diagrams

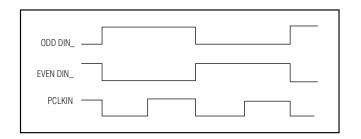


Figure 1. Serializer Worst-Case Switching Pattern

Figure 2. Deserializer Worst-Case Switching Pattern

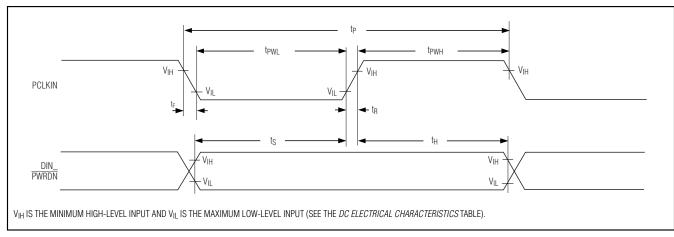


Figure 3. Serializer Input Timing

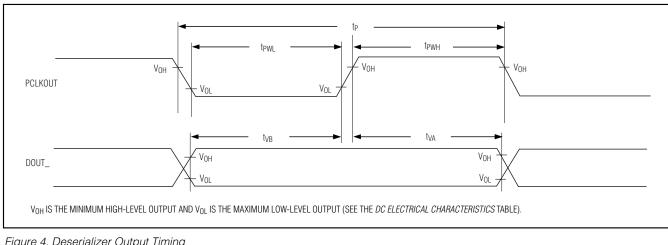
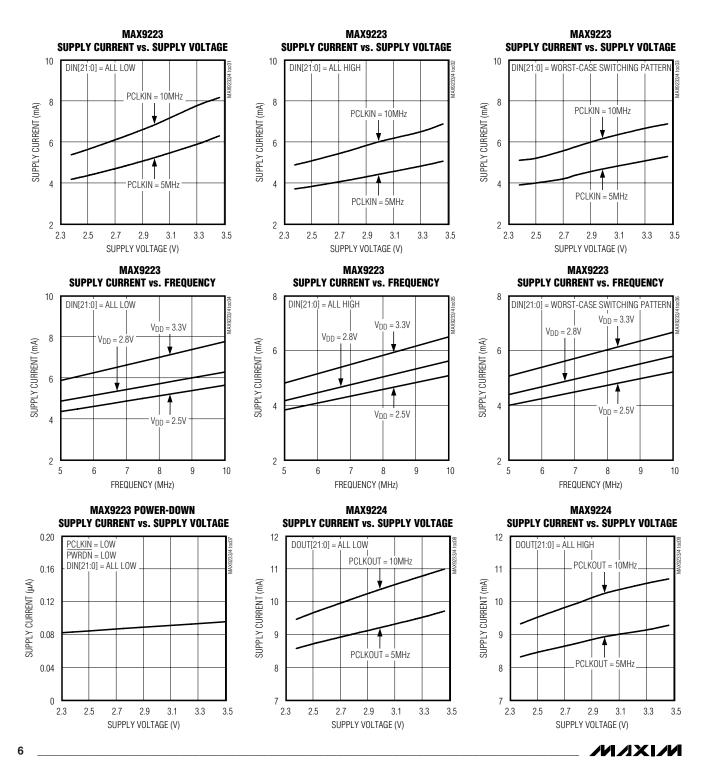


Figure 4. Deserializer Output Timing

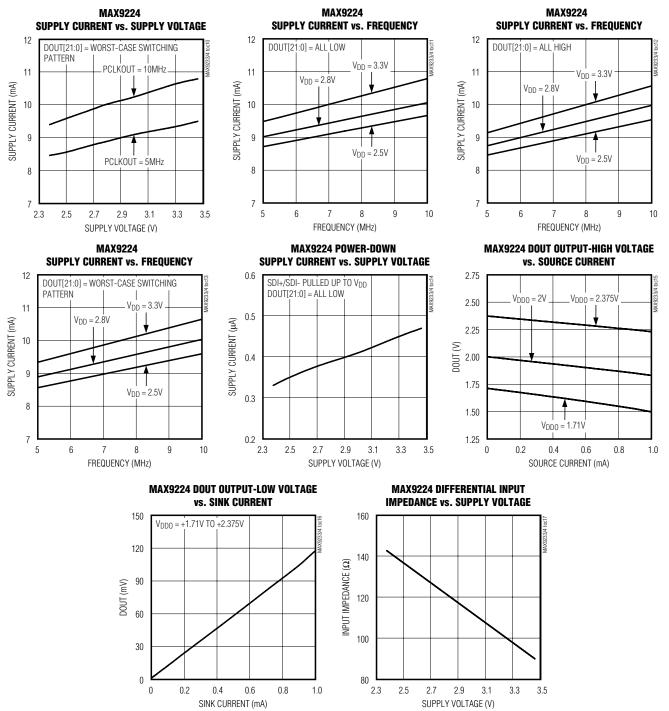
Typical Operating Characteristics

 $(V_{DD} = V_{DDO} = +2.8V)$, logic input levels = 0 to +2.8V, logic output load $C_L = 5pF$, $T_A = +25^{\circ}C$, unless otherwise noted.)



Typical Operating Characteristics (continued)

 $(V_{DD} = V_{DDO} = +2.8V)$, logic input levels = 0 to +2.8V, logic output load $C_L = 5pF$, $T_A = +25^{\circ}C$, unless otherwise noted.)



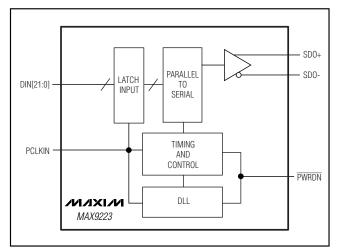
Pin Description (MAX9223)

PIN	NAME	FUNCTION
1–12, 14, 15, 21–28	DIN13–DIN2, DIN1, DIN0, DIN21–DIN14	Single-Ended Parallel Data Inputs. The 22 data bits are loaded into the input latch on the rising edge of PCLKIN. DIN[9:0] are 1.71V to 3.465V tolerant. Internally pulled down to GND.
13	PCLKIN	Parallel Clock Input. The rising edge of PCLKIN (typically the pixel clock) latches the parallel data input. Internally pulled down to GND.
16	PWRDN	Power-Down Input. Pull PWRDN low to place the MAX9223 and MAX9224 in power-down mode. Drive PWRDN high for normal operation. Internally pulled down to GND.
17	SDO-	Inverting LCDS Serial-Data Output
18	SDO+	Noninverting LCDS Serial-Data Output
19	GND	Ground
20	V _{DD}	Core Supply Voltage. Bypass to GND with 0.1μ F and 0.01μ F capacitors in parallel as close to the device as possible, with the smallest value capacitor closest to the supply pin.
	EP	Exposed Paddle. Connect EP to ground.

Pin Description (MAX9224)

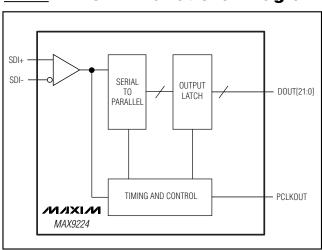
PIN	NAME	FUNCTION
1, 7, 8, 10–28	DOUT21, DOUT0, DOUT1, DOUT2–DOUT20	Single-Ended Parallel Data Outputs. DOUT[21:0] are valid on the rising edge of PCLKOUT.
2	V _{DDO}	Output Supply Voltage. Bypass to GND with 0.1μ F and 0.01μ F capacitors in parallel as close to the device as possible, with the smallest value capacitor closest to the supply pin.
3	GND	Ground
4	SDI+	Noninverting LCDS Serial-Data Input
5	SDI-	Inverting LCDS Serial-Data Input
6	V _{DD}	Core Supply Voltage. Bypass to GND with 0.1μ F and 0.01μ F capacitors in parallel as close to the device as possible, with the smallest value capacitor closest to the supply pin.
9	PCLKOUT	Parallel Clock Output. Parallel output data are valid on the rising edge of PCLKOUT (typically the pixel clock).
	EP	Exposed Paddle. Connect EP to ground.

MAX9223 Functional Diagram



Detailed Description

The MAX9223 serializer operates at a 5MHz to 10MHz parallel clock frequency, serializing 22 bits of parallel input data DIN[21:0] in each cycle of the parallel clock. DIN[21:0] are latched on the rising edge of PCLKIN. The data and internally generated serial clock are combined and transmitted through SDO+/SDO- using multi-level LCDS. The MAX9224 deserializer receives the LCDS signal on SDI+/SDI-. The deserialized data and recovered parallel clock are available at DOUT[21:0]



_MAX9224 Functional Diagram

and PCLKOUT. Output data is valid on the rising edge of PCLKOUT.

The first bit (G) is internally grounded and transmitted first. Bit 0 (DIN[0]) is the first valid data bit. Boundary bits OH are used by the MAX9224 deserializer to identify the word boundary and are the inverse polarity of data bit 21 (DIN[21]). Therefore, at least one level transition is guaranteed in one word. The clock is recovered from the serial input.

Serial word format:

G	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	ОН	ОН

LCDS

The MAX9223/MAX9224 use a proprietary multilevel LCDS interface. Figure 5 provides a representation of the data and clock in the multilevel LCDS interface. This interface offers advantages over other chipsets, such as requiring only one differential pair as the transmission medium, the inherently aligned data and clock, and much smaller current levels than the 4mA typically found in traditional LVDS interfaces.

MAX9223/MAX9224 Handshaking

The handshaking function of the MAX9223/MAX9224 provides bidirectional communication between the two devices in case a word boundary error is detected. Prior

to data transmission, the MAX9223 serializer adds boundary bits (OH) to the end of the latched word. These boundary bits are the inverse of the last bit of the latched word. During data transmission, the MAX9224 deserializer continuously monitors the state of the boundary bits of each word. If a word boundary error is detected, the serial link is pulled up to V_{CC} and the MAX9224 powers down. The MAX9223 detects the pullup of the serial link and powers down for 1.0µs. After 1.0µs, the MAX9223 powers up, causing the power-up of the MAX9224. Then the word boundary is reestablished, and data transfer resumes. The handshaking function is disabled when PWRDN is pulled low.



MAX9223/MAX9224

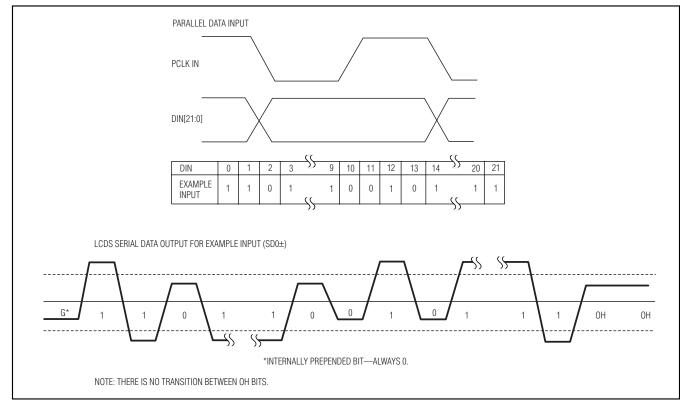


Figure 5. Multilevel LCDS Output Representation

Applications Information

PCLKIN Latch Edge

The parallel data input of the MAX9223 serializer is latched on the rising edge of PCLKIN. Figure 3 shows the serializer input timing.

PCLKOUT Strobe

The serial-data output of the MAX9224 deserializer is valid on the rising edge of PCLKOUT. Figure 4 shows the deserializer output timing.

Power-Down and Power-Off

Driving $\overline{\text{PWRDN}}$ low puts the MAX9223 in power-down mode and sends a pulse to power down the MAX9224. In power-down mode, the DLL is stopped, SDO+/SDO- are high impedance to ground and differential, and the LCDS link is weakly biased around V_{DD} - 0.8V. With $\overline{\text{PWRDN}}$ and all inputs low, the combined MAX9223/MAX9224 supply current is reduced to 3.5µA or less.

Driving PWRDN high starts DLL lock to PCLKIN and initiates a MAX9224 power-up sequence. The MAX9223 LCDS output is not driven until the DLL locks. 4096 clock cycles are required for the power-up and link synchronization, before valid DIN can be latched. See Figure 6 for an overall power-up and power-down timing diagram. For normal operation, PCLKIN must be running and settled before driving PWRDN high.

If $V_{DD} = 0$, the LCDS outputs are high impedance to ground and differential.

Ground-Shift Tolerance

M/IXI/N

The MAX9223/MAX9224 are designed to function normally in the event of a slight shift in ground potential. However, the MAX9224 deserializer ground must be within $\pm 0.2V$ relative to the MAX9223 serializer ground to maintain proper operation.

MAX9224 Output Buffer Supply (VDDO)

The MAX9224 parallel outputs are powered from V_{DDO}, which accepts a +1.71V to +3.465V supply, allowing direct interface to inputs with 1.8V to 3.3V logic levels.

MAX9223/MAX9224

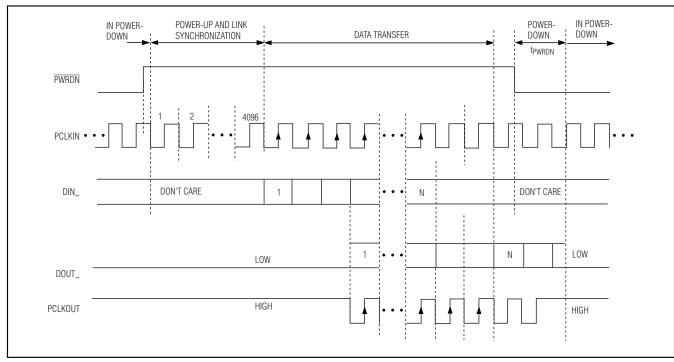


Figure 6. MAX9223/MAX9224 Power-Up/Power-Down Sequence

Flex Cable, PCB Interconnect, and Connectors

Interconnect for LCDS typically has a differential impedance of 110Ω . Use interconnect and connectors that have matched differential impedance to minimize impedance discontinuities.

Board Layout and Supply Bypassing

Separate the logic and LCDS signals to prevent crosstalk. A PCB or flex with separate layers for power, ground, and signals is recommended.

Bypass each V_{DD} and V_{DDO} pin with high-frequency, surface-mount ceramic 0.1μ F and 0.01μ F capacitors in parallel as close to the device as possible, with the smallest value capacitor closest to the supply pin.

ESD Protection

The MAX9223/MAX9224 LCDS inputs and outputs (SDO+/SDO-, SDI+/SDI-) are rated for \pm 15kV ESD protection using the Human Body Model. The Human Body Model discharge components are C_S = 100pF and R_D = 1.5k Ω (Figure 7).

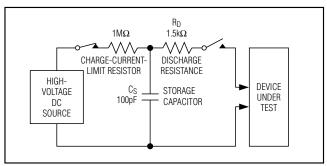


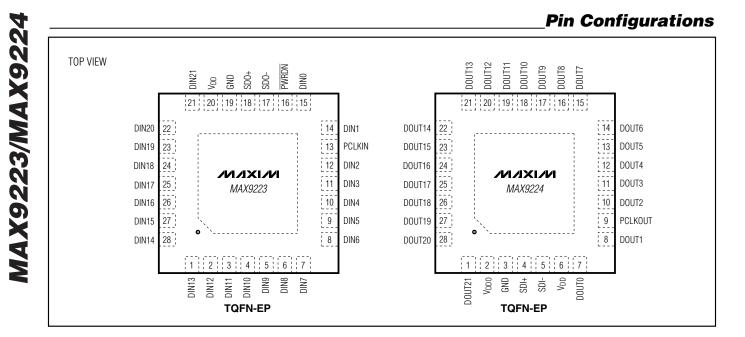
Figure 7. Human Body Model ESD Test Circuit

Chip Information

PROCESS: CMOS

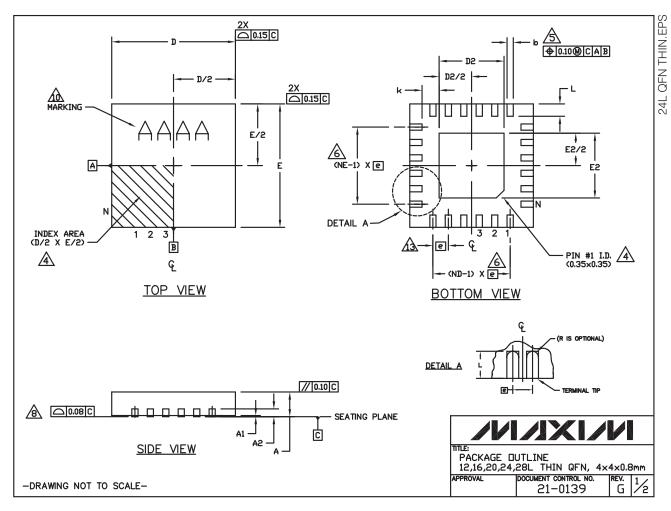
MAX9223/MAX9224





Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to www.maxim-ic.com/packages.)

				_	COM		DIM	IENS	IONS								
PKG	12	2L 4×	4	16L 4×4			20)L 4×	4	24	4L 4×	:4	28L 4×4				
REF.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX		
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80		
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05		
A2	0	.20 RE	F	0	20 RE	F	0	.20 RE	F	0	20 RE	F	0	20 RE	F		
ю	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	0.15	0.20	0.25		
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10		
Е	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10		
e		.80 BS	с.	0.65 BSC.			0.50 BSC.		0.50 BSC.			0.40 BSC.					
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-		
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.30	0.40	0.50		
N		12			16			20			24			28			
ND		3		4				5		6			7				
NE		3			4			5		6			7				
Jedec Vor.		WGGB			WGGC		1	/GGD-:	L		WGGD-	5		WGGE	WGGE		

EXPOSED PAD VARIATIONS												
PKG.		D2			E2							
CODES	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.						
T1244-3	1.95	2.10	2.25	1.95	2.10	2.25						
T1244-4	1.95	2.10	2.25	1.95	2.10	2.25						
T1644-3	1.95	2.10	2.25	1.95	2.10	2.25						
T1644-4	1.95	2.10	2.25	1.95	2.10	2.25						
T2044-2	1.95	2.10	2.25	1.95	2.10	2.25						
T2044-3	1.95	2.10	2.25	1.95	2.10	2.25						
T2444-2	1.95	2.10	2.25	1.95	2.10	2.25						
T2444-3	2.45	2.60	2.63	2.45	2.60	2.63						
T2444-4	2.45	2.60	2.63	2.45	2.60	2.63						
T2844-1	2.50	2.60	2.70	2.50	2.60	2.70						

////////////

PACKAGE DUTLINE 12,16,20,24,28L THIN QFN, 4×4×0.8mm PPROVAL DOCUMENT CONTROL NO. REV. 2/

21-0139

NOTES

MAX9223/MAX9224

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.

🗥 THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.

- 🕭 DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25mm AND 0.30mm FROM TERMINAL TIP.
- AND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- 7. DEPUPULATION IS POSSIBLE IN A SYMMETRICAL FASTION.
- DRAWING CONFORMS TO JEDEC MO220, EXCEPT FOR T2444-3, T2444-4 AND T2844-1.
- 9. DRAWING CONFORMS TO JEDEC MO220, EXCEPT FOR T2444
- 11. COPLANARITY SHALL NOT EXCEED 0.08mm.
- 12. WARPAGE SHALL NOT EXCEED 0.10mm.
- 14. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- 15. ALL DIMENSIONS ARE THE SAME FOR LEADED (-) & PbFREE (+) PACKAGE CODES.

-DRAWING NOT TO SCALE-

REV. 2/

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/05	Initial release	
1	12/07	Changed min output short-circuit current from -20 to -25 and updated package outlines.	3, 13

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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